

Specification for Approval

Date: 2024/11/09

Customer : 信和達

TAI-TECH P/N: TMPF0403LRV-Series(N)-ABD-HD

CUSTOMER P/N: _____

DESCRIPTION: _____

QUANTITY: _____ pcs

REMARK:		
Customer Approval Feedback		

西北臺慶科技股份有限公司
 TAI-TECH Advanced Electronics Co., Ltd
Headquarter:
 NO.1 YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI,
 TAO-YUAN HSIEN, TAIWAN, R.O.C.
 TEL: +886-3-4641148 FAX: +886-3-4643565
 http://www.tai-tech.com.tw
 E-mail: sales@tai-tech.com.tw

Sales Dep.

APPROVED	CHECKED
Eric Kuan	Zhang mengmeng

臺慶精密電子(昆山)有限公司
 TAI-TECH ADVANCED ELECTRONICS(KUNSHAN) CO., LTD
 SHINWHA ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN,
 JIANG-SU, CHINA
 TEL: +86-512-57619396 FAX: +86-512-57619688
 E-mail: sales@tai-tech.cn

R&D Center

APPROVED	CHECKED	DRAWN
Sky Luo	Mr.Liang	Cui lingling

慶邦電子元器件(泗洪)有限公司
 TAIPAQ ELECTRONICS (SIHONG) CO., LTD
 THE SOUTH HANGZHOU ROAD AND THE EAST JIAN SHE BEI
 ROAD,ECONOMIC DEVELOPMENT ZONE,SIHONG COUNTY,
 JIANGSU PROVINCE,P.R.CHINA.
 TEL: +86-527-88601191 FAX: +86-527-88601190
 E-mail: sales@taipaq.cn

SMD Power Inductor

TMPF0403LRV-Series(N)-ABD-HD

ECN HISTORY LIST

REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	24/11/09	New Issue	Sky Luo	Mr.Liang	Cui lingling
備 注					

SMD Power Inductor

1. Features

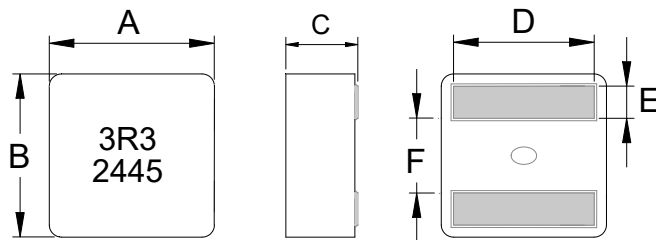
1. Low loss realized with low DCR.
2. High performance realized by metal dust core.
3. Ultra low buzz noise, due to composite construction.
4. 100% Lead(Pb)-Free and RoHS compliant.
5. High reliability -Reliability test complied to AEC-Q200.



2. Applications

Automotive applications.

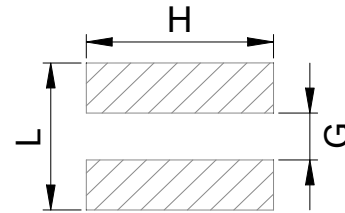
3. Dimensions



A	B	C	D	E	F
4.40±0.20	4.40±0.20	2.80±0.20	3.40±0.30	0.88±0.20	1.60±0.25

Unit:mm

Recommend PC Board Pattern



L	G	H
3.4 ref	1.4 ref	3.8 ref

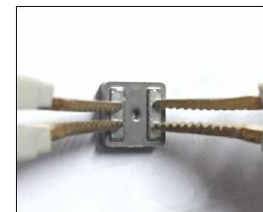
Note: 1.PCB layout is referred to standard IPC-7351B
 2. The above PCB layout reference only.
 3. Recommend solder paste thickness at 0.12mm and above.

4. Part Numbering



- A: Series
- B: Dimension
- C: Type
- D: Inductance
- E: Inductance Tolerance
- F: DateCode
- G: Code

BxC
 Material.
 3R3=3.30uH
 M=±20%
 Marking: Black.3R3 and 2445 (24 YY,45 WW, follow production date).
 AB:oversize



DCR Test

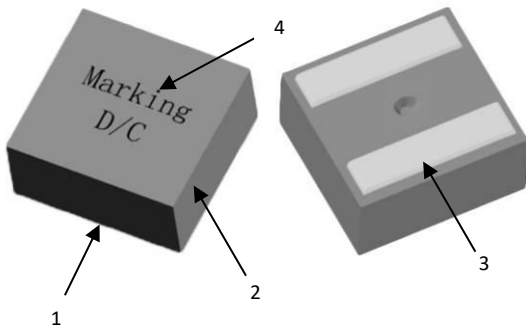
5. Specification

Part Number	Inductance (uH) $\pm 20\%$ @ 0 A	I rms (A) Typ		I sat (A)				DCR (m Ω)	
		20 $^{\circ}$ C rise	40 $^{\circ}$ C rise	Typ			Max	Typ	Max
				1	2	3	3		
TMPF0403LRV-R90MN-ABD-HD	0.90	8.2	11.2	5.2	7.0	10.0	9.0	9.1	10.1
TMPF0403LRV-1R0MN-ABD-HD	1.00	8.0	11.0	5.0	6.8	9.8	9.2	9.1	10.1
TMPF0403LRV-1R2MN-ABD-HD	1.20	7.8	9.8	4.6	6.4	9.2	8.7	10.4	11.5
TMPF0403LRV-1R5MN-ABD-HD	1.50	7.0	9.0	4.1	5.6	8.0	7.0	12.0	13.2
TMPF0403LRV-1R8MN-ABD-HD	1.80	6.5	8.2	3.8	5.3	7.5	6.6	17.4	19.2
TMPF0403LRV-2R2MN-ABD-HD	2.20	6.0	7.8	3.6	5.1	7.0	6.1	20.5	22.6
TMPF0403LRV-3R3MN-ABD-HD	3.30	5.0	6.6	3.3	4.8	6.2	5.3	26.0	28.6
TMPF0403LRV-4R7MN-ABD-HD	4.70	3.9	5.1	2.8	4.2	5.5	4.8	40.1	44.1

Note:

1. Test frequency : L : 100KHz /0.1V.
2. All test data referenced to 25 $^{\circ}$ C ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Current that causes the specified temperature rise from 25 $^{\circ}$ C ambient.
5. Saturation Current (Isat 1) will cause L0 to drop approximately 10%.
Saturation Current (Isat 2) will cause L0 to drop approximately 20%.
Saturation Current (Isat 3) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 155 $^{\circ}$ C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Irms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components.
Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of Irms and Isat.

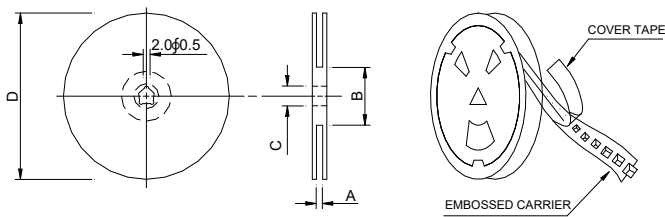
6. Material List



NO	Items	Materials
1	Core	Alloy powder.
2	Wire	Polyester Wire or equivalent.
3	Solder	100% Pb free solder
4	Ink	Halogen-free ketone

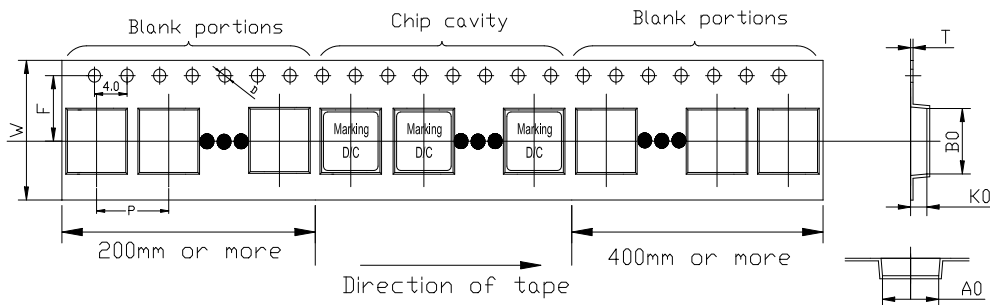
7. Packaging Information

(1) Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x12mm	12.4+2/-0	100±2	13+0.5/-0.2	330

(2) Tape Dimension



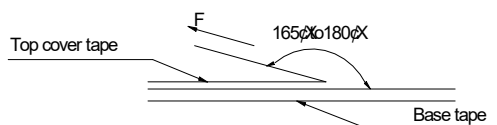
B0	A0	K0	P	W	F	T	D
4.7±0.1	4.7±0.1	3.3±0.1	8.0±0.1	12±0.3	5.5±0.1	0.35±0.1	1.5±0.1

Unit:mm

(3) Packaging Quantity

TMPF	0403
Chip / Reel	2000

(4) Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-D-2008 of 4.11 stadnard).

Tearing Speed mm	Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)
300 ± 10%	5~35	45~85	860~1060

8. Reliability and Test Condition

Item	Performance	Test Condition																												
Operating temperature	-55~+155°C(Including self - temperature rise)	NA																												
Storage temperature and Humidity range	1. -10~+40°C, 50~60%RH (Product with taping) 2. -55~+155°C(on board)	NA																												
Electrical Performance Test																														
Inductance	Refer to standard electrical characteristics list.	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR Meter.																												
DCR		CH16502, Agilent33420A Micro-Ohm Meter.																												
Saturation Current (Isat)	Approximately ΔL30%	Saturation DC Current (Isat) will cause L0 to drop ΔL(%).																												
Heat Rated Current (Irms)	Approximately ΔT40°C	Heat Rated Current (Irms) will cause the coil temperature rise ΔT(°C). 1. Applied the allowed DC current. 2. Temperature measured by digital surface thermometer.																												
Reliability Test (For AEC-Q200-E)																														
8.1	Pre- and Post-Stress Electrical Test User Specification	Test is performed at room temperature except as specified in the applicable stress reference and the additional requirements in this Table (e.g. 8.3, 8.4, 8.5) Preconditioning : run through reflow for 3 times. (IPC/JEDECJ-STD-020F Classification Reflow Profiles)																												
8.2	High Temperature Exposure(Storage) Reference MIL-STD-202 Method 108	Unpowered, Temperature : 155±2°C Upper Temperature: maximum specified operating temperature or maximum specified storage temperature (whichever is higher). Duration : 1000hrs Min. Measured at room temperature after placing for 24±4 hrs.																												
8.3	Temperature Cycling Reference JESD22-A104	Conduct Temperature Cycling testing on the product after performing the Pre- and Post-Stress Electrical Tests as specified in section 8.1 Unpowered Lower Temperature of the Chamber: -40°C(For Inductors/Transformers) Upper Temperature of the Chamber: maximum specified operating temperature and shall not exceed 125°C Condition for 1 cycle Step1 : -40±2°C 30min Min. Step2 : 125±2°C transition time 1min MAX Step3 : 125±2°C 30min Min. Step4 : Dwell Time (Soak Time) 15 minutes minimum, 30 minutes minimum if component weighs above 28g Transition Time : 1 minute maximum Number of cycles : 1000 Measured at room temperature at least 24 hours after test conclusion.																												
8.4	Humidity Bias Reference MIL-STD-202 Method 103	Conduct Humidity Bias testing on the product after performing the Pre- and Post-Stress Electrical Tests as specified in section 8.1 Unpowered(For Inductors/Transformers) Humidity : 85±3% R.H, Temperature : 85°C±2°C Duration : 1000hrs Min. Measured at room temperature after placing for 24±4hrs.																												
8.5	High Temperature Operating Life Reference MIL-STD-202 Method 108	Conduct High Temperature Operating Life testing on the product after performing the Pre- and Post-Stress Electrical Tests as specified in section 8.1 Temperature : 115±2°C Upper Temperature of the Chamber: maximum specified operating temperature (not including heat rise) at maximum rated power and shall not exceed 125°C. (For Inductors/Transformers) Duration : 1000hrs Min. with 100% rated current. Measured at room temperature after placing for 24±4 hrs.																												
8.6	External Visual Reference MIL-STD-883 Method 2009	Appearance : no damage. Inspect device construction, marking and workmanship. Pre and Post Electrical Test not required.																												
8.7	Physical Dimension Reference JESD22-B100	According to the product specification size measurement. Verify physical dimensions to the applicable component detail specification. Pre and Post Electrical Test not required.																												
8.8	Terminal Strength (for axial and radial THT components) Reference MIL-STD-202 Method 211	Test THT component lead integrity only. Test Condition A (pull test) <table border="1"> <thead> <tr> <th>Nominal cross-sectional area(mm²)</th> <th>Force (N)</th> </tr> </thead> <tbody> <tr> <td>≤0.05</td> <td>1</td> </tr> <tr> <td>0.06 to 0.10</td> <td>2.5</td> </tr> <tr> <td>0.11 to 0.20</td> <td>5</td> </tr> <tr> <td>0.21 to 0.50</td> <td>10</td> </tr> <tr> <td>0.51 to 1.20</td> <td>20</td> </tr> <tr> <td>>1.20</td> <td>40</td> </tr> </tbody> </table> Test Condition C (wire-lead bend test) : <table border="1"> <thead> <tr> <th>Section Modulus (Zx) (mm³)</th> <th>Force (N)</th> </tr> </thead> <tbody> <tr> <td>≤1.5x10⁻³</td> <td>0.5</td> </tr> <tr> <td>1.6x10⁻³ to 4.2x10⁻³</td> <td>1.25</td> </tr> <tr> <td>4.3x10⁻³ to 1.2x10⁻²</td> <td>2.5</td> </tr> <tr> <td>1.3x10⁻² to 0.5x10⁻¹</td> <td>5</td> </tr> <tr> <td>0.6x10⁻¹ to 1.9x10⁻¹</td> <td>10</td> </tr> <tr> <td>> 1.9x10⁻¹</td> <td>20</td> </tr> </tbody> </table> For round terminations : ZX = (πd ³)/32 where d is the lead diameter. For strip terminations : ZX = (ba ²)/6 where a is the thickness of the rectangular strip perpendicular to the bending axis, b is the other dimension of the rectangular strip.	Nominal cross-sectional area(mm ²)	Force (N)	≤0.05	1	0.06 to 0.10	2.5	0.11 to 0.20	5	0.21 to 0.50	10	0.51 to 1.20	20	>1.20	40	Section Modulus (Zx) (mm ³)	Force (N)	≤1.5x10 ⁻³	0.5	1.6x10 ⁻³ to 4.2x10 ⁻³	1.25	4.3x10 ⁻³ to 1.2x10 ⁻²	2.5	1.3x10 ⁻² to 0.5x10 ⁻¹	5	0.6x10 ⁻¹ to 1.9x10 ⁻¹	10	> 1.9x10 ⁻¹	20
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Item		Performance	Test Condition																																														
8.9	Resistance to Solvents Reference MIL-STD-202 Method 215		Add an Aqueous wash chemical and follow chemical manufacturer's recommended parameters (i.e. solution temperature and immersion time). Applicable to ink marked components and not laser marked components																																														
8.10	Mechanical Shock Reference MIL-STD-202 Method 213		<table border="1"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (Vi)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>100</td> <td>6</td> <td>Half-sine</td> <td>12.3</td> </tr> <tr> <td>THT</td> <td>100</td> <td>6</td> <td>Half-sine</td> <td>12.3</td> </tr> </tbody> </table> <p>3 shocks in each direction along 3 perpendicular axes. (18 shocks).</p>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	SMD	100	6	Half-sine	12.3	THT	100	6	Half-sine	12.3																															
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8.11	Vibration Reference MIL-STD-202 Method 204		Oscillation Frequency : 10Hz~2kHz~10Hz for 20 minutes Equipment : Vibration checker Total Amplitude : 5g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)																																														
8.12	Resistance to Soldering Heat Reference MIL-STD-202 Method 210	Appearance : no damage. Inductance : within ±10% of initial value DCR : within ±15% of initial value and shall not exceed the specification value.	<p>Test condition : THT : Conditions B or C</p> <table border="1"> <thead> <tr> <th>Solder technique simulation</th> <th>Test condition</th> <th>Temperature (°C)</th> <th>Time(s)</th> <th>Temperature ramp/immersion and emersion rate</th> <th>Number of heat cycles</th> </tr> </thead> <tbody> <tr> <td>Dip</td> <td>B</td> <td>260 ±5 (solder temp)</td> <td>10±1</td> <td>25mm/s ±6mm/s</td> <td>1</td> </tr> <tr> <td>Wave : Topside board-mount product</td> <td>C</td> <td>260 ±5 (solder temp)</td> <td>20±1</td> <td></td> <td>1</td> </tr> </tbody> </table> <p>Depth : completely cover the termination SMD : Condition K, time above 217° C, 60s-150s, Number of heat cycles : 3 Continental</p> <p>Table 1 : Minimum requirements for lead-free soldering</p> <table border="1"> <thead> <tr> <th>Component Size</th> <th>Ramp up to 150°C</th> <th>T_{smin}</th> <th>T_s</th> <th>T_{smax}</th> <th>T_L</th> <th>t_L</th> <th>T_{peak}*</th> <th>T_p**</th> <th>Time 25°C to peak</th> <th>Ramp down</th> </tr> </thead> <tbody> <tr> <td>Thickness < 1.6mm or Thickness 1.6mm-2.5mm and Volume < 350mm³</td> <td rowspan="3">3.0 ± 0.1°C/s (The component shall be specified for usage in serial production with up to 3.0°C/s)</td> <td>≥ 190°C</td> <td>≥ 110s</td> <td>≥ 200°C</td> <td>≥ 217°C</td> <td>≥ 90s</td> <td>≥ 260°C</td> <td>≥ 40s</td> <td rowspan="3">≥ 300s</td> <td rowspan="3">6.0 ± 0.1°C/s (The component shall be specified for usage in serial production with up to 6.0°C/s)</td> </tr> <tr> <td>Thickness 1.6mm-2.5mm and Volume < 350-2000mm³ or Thickness > 2.5mm and Volume < 350mm³</td> <td>≥ 250°C</td> <td>≥ 30s</td> </tr> <tr> <td>Thickness 1.6mm-2.5mm and Volume > 2000mm³ or Thickness > 2.5mm and Volume > 350mm³</td> <td>≥ 245°C</td> <td></td> </tr> </tbody> </table> <p>*peak temperature is measured on the centre top of the component package **tp measured @ T peak-5°C</p>	Solder technique simulation	Test condition	Temperature (°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	Dip	B	260 ±5 (solder temp)	10±1	25mm/s ±6mm/s	1	Wave : Topside board-mount product	C	260 ±5 (solder temp)	20±1		1	Component Size	Ramp up to 150°C	T _{smin}	T _s	T _{smax}	T _L	t _L	T _{peak} *	T _p **	Time 25°C to peak	Ramp down	Thickness < 1.6mm or Thickness 1.6mm-2.5mm and Volume < 350mm ³	3.0 ± 0.1°C/s (The component shall be specified for usage in serial production with up to 3.0°C/s)	≥ 190°C	≥ 110s	≥ 200°C	≥ 217°C	≥ 90s	≥ 260°C	≥ 40s	≥ 300s	6.0 ± 0.1°C/s (The component shall be specified for usage in serial production with up to 6.0°C/s)	Thickness 1.6mm-2.5mm and Volume < 350-2000mm ³ or Thickness > 2.5mm and Volume < 350mm ³	≥ 250°C	≥ 30s	Thickness 1.6mm-2.5mm and Volume > 2000mm ³ or Thickness > 2.5mm and Volume > 350mm ³	≥ 245°C	
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8.13	ESD Reference AEC-Q200-002		<p>Direct Contact and Air Discharge PASSIVE COMPONENT HBM ESD Discharge Waveform to a Coaxial Target Test method : AEC-Q200-002 Test mode : Contact Discharge Discharge level : 4 KV (Level : 2)</p>																																														

Item		Performance	Test Condition																																
8.14	Solderability Reference J-STD-002	More than 95% of the terminal electrode should be covered with solder.	<p>Through-hole Technology (THT : Method A1, Coating Durability Category 2)</p> <ul style="list-style-type: none"> SMD : <ul style="list-style-type: none"> Method B1, Coating Durability Category 2 Method D, Coating Durability Category 2 Magnification 50x Pre and Post Electrical Test not required. Non-soldered type mounting/attach are not applicable. <table border="1"> <thead> <tr> <th>Reference</th> <th>Method A1</th> <th>Method B1</th> <th>Method D</th> </tr> </thead> <tbody> <tr> <td>Welding Process</td> <td>Reflow Soldering</td> <td>Reflow Soldering for Other Components</td> <td>Lead-free Soldering</td> </tr> <tr> <td>Type of Solder</td> <td>Tin-Silver-Copper Solder</td> <td>Tin-Silver-Copper Solder</td> <td>Tin-Silver-Copper Solder</td> </tr> <tr> <td>Flux Immersion Time</td> <td>5-10s</td> <td>5-10s</td> <td>5-10s</td> </tr> <tr> <td>Immersion Angle</td> <td>20°~45°</td> <td>20°~45°</td> <td>20°~45°</td> </tr> <tr> <td>Solder Temperature</td> <td>245±5° C</td> <td>245±5° C</td> <td>260±5° C</td> </tr> <tr> <td>Solder Immersion Time</td> <td>5+0/-0.5s</td> <td>5+0/-0.5s</td> <td>30+5/-0s</td> </tr> <tr> <td>Speed of Immersion and Withdrawal</td> <td>25±6mm/s</td> <td>25±6mm/s</td> <td>25±6mm/s</td> </tr> </tbody> </table>	Reference	Method A1	Method B1	Method D	Welding Process	Reflow Soldering	Reflow Soldering for Other Components	Lead-free Soldering	Type of Solder	Tin-Silver-Copper Solder	Tin-Silver-Copper Solder	Tin-Silver-Copper Solder	Flux Immersion Time	5-10s	5-10s	5-10s	Immersion Angle	20°~45°	20°~45°	20°~45°	Solder Temperature	245±5° C	245±5° C	260±5° C	Solder Immersion Time	5+0/-0.5s	5+0/-0.5s	30+5/-0s	Speed of Immersion and Withdrawal	25±6mm/s	25±6mm/s	25±6mm/s
Reference	Method A1	Method B1	Method D																																
Welding Process	Reflow Soldering	Reflow Soldering for Other Components	Lead-free Soldering																																
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Solder Immersion Time	5+0/-0.5s	5+0/-0.5s	30+5/-0s																																
Speed of Immersion and Withdrawal	25±6mm/s	25±6mm/s	25±6mm/s																																
8.15	Electrical Characterization	Refer Specification for Approval.	Parametrically test per lot and sample size requirements, summary to show Min, Max, Mean and Standard deviation at room as well as Min and Max operating temperatures. Pre and Post Electrical Test not required																																
8.16	Board Flex(SMD) Reference AEC-Q200-005	Appearance : no damage. Inductance : within ± 10% of initial value DCR : within ± 15% of initial value and shall not exceed the specification value.	<p>Preconditioning : run through reflow for 3 times. (IPC/JEDEC J-STD-020F Classification Reflow Profiles) Place the 100mm X 40mm board into a fixture similar to the one shown in below Figure with the component facing down. The apparatus shall consist of mechanical means to apply a force which will bend the board (D) x = 2 mm minimum. The duration of the applied forces shall be 60 (+ 5) sec. The force is to be applied only once to the board.</p>																																
8.17	Terminal Strength(SMD) Reference AEC-Q200-006		<p>With the component mounted on a PCB with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.</p>																																

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.

9. Soldering Specifications

(1) Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

(2) Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020F)

(3) Iron Reflow:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.(Fig. 2)

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.

Fig.1 Soldering Reflow

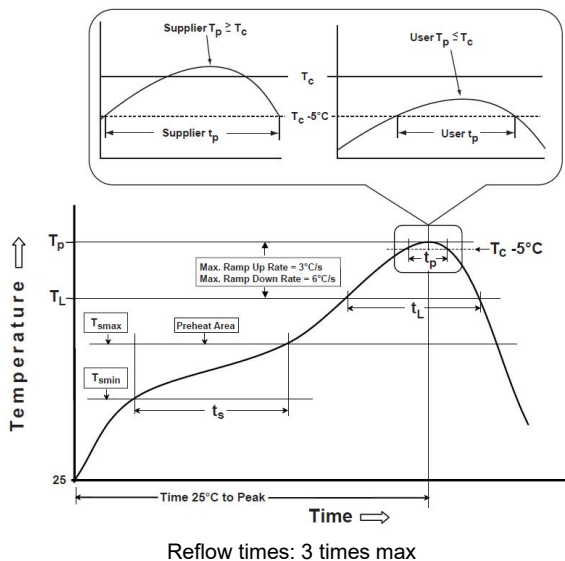


Fig.2 Iron soldering temperature profiles

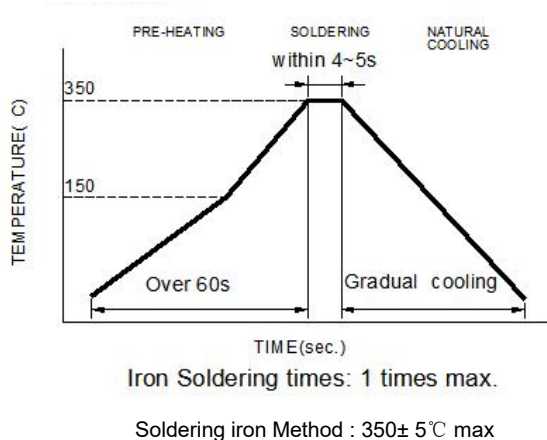


Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat	
-Temperature Min(T_{smin})	150°C
-Temperature Max(T_{smax})	200°C
-Time(t_s)from(T_{smin} to T_{smax})	60-120seconds
Ramp-up rate(T_L to T_p)	3°C/second max.
Liquidus temperature(T_L)	217°C
Time(t_L)maintained above T_L	60-150 seconds
Classification temperature(T_c)	See Table (1.2)
Time(t_p) at $T_c - 5^\circ\text{C}$ (T_p should be equal to or less than T_c .)	* < 30 seconds
Ramp-down rate(T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

T_p : maximum peak package body temperature, T_c : the classification temperature.

For user (customer) T_p should be equal to or less than T_c .

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020F.

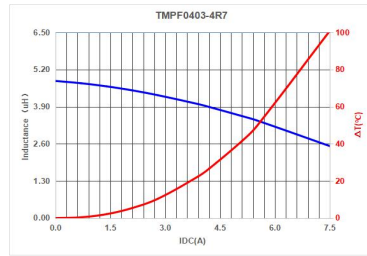
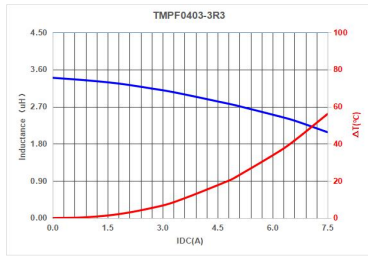
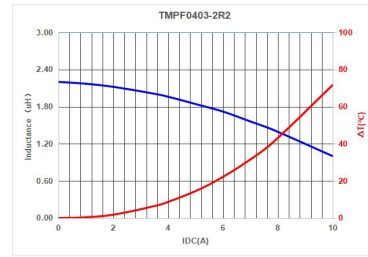
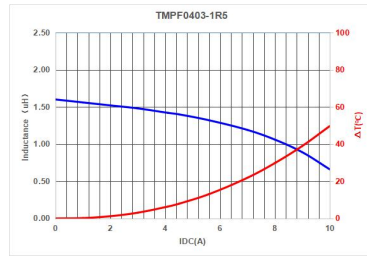
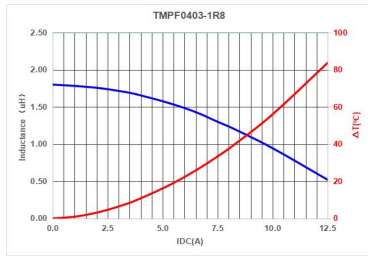
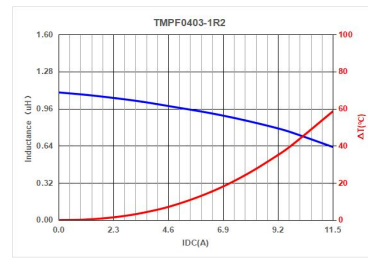
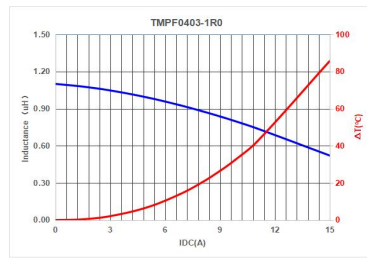
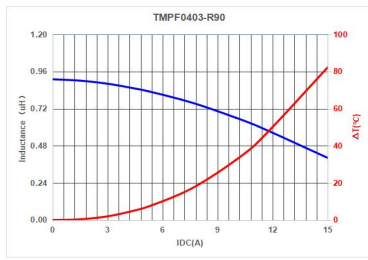
10. Notes

- (1) When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition
- (2) This power choke coil itself does not have any protective function in abnormal condition such as overload, short-circuit and open-circuit conditions, etc. Therefore, it shall be confirmed as the end product that there is no risk of smoking, fire, dielectric withstand voltage, insulation resistance, etc. in abnormal conditions to provide protective devices and/or protection circuit in the end product.
- (3) When this power choke coil was used in a similar or new product to the original one, sometimes it might not be able to satisfy the specifications due to different condition of use.
- (4) Dielectric withstanding test with higher voltage than specific value will damage insulating material and shorten its life.
- (5) This power choke coil must not be used in wet condition by water, coffee or any liquid because insulation strength becomes very low in this condition.
- (6) Please consult our company to confirm the reliability of the process required to wash or use or exposure to a chemical solvent used in this product. PCB washing tested to MIL-STD-202 Method, and dry it off immediately.
- (7) The rated current as listed is either the saturation current or the heating current depending on which value is lower.
- (8) If this power choke is dipped in the cleaning agent, such as toluene, xylene, ketone, and ether system, there is a possibility that the performance decreases greatly, and marking disappears.
- (9) The high power ultrasonic washing may damage the choke body.
- (10) Before use, the user should determine whether this product is suitable for their own design. Our company only guarantees that the product meets the requirements of this specification.

Application Notice

- Storage Conditions
 - To maintain the solderability of terminal electrodes:
 1. TAI-TECH products meet IPC/JEDEC J-STD-020F standard-MSL, level 1.
 2. Temperature and humidity conditions: Less than 40°C and 85% RH.
 3. Recommended products should be used within 12 months from the time of delivery.
 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

11. Typical Performance Curves



单击下面可查看定价，库存，交付和生命周期等信息

[>>TAI-TECH\(台庆\)](#)